









PRODUCT DATASHEET



- ► PTH Display
- ▶ 0.56" (14.2mm) 8.8.
- ► Green (572nm)

N0G47D71GS **N0G47D71GS**



PTH Display Series Compliant





Package: PTH Numeral Double Digits Display

Forward Current: 20mA per diode

Forward Voltage (typ.): 2.0V per diode

Luminous Intensity (typ.): 18mcd@20mA per diode

Colour: Green

Wavelength: 572nm

Materials:

FEATURES:

Die: AlInGaP

Resin: Epoxy (White Diffused)

Surface Colour: Grey

Operating Temperature: -40~+85°C

Storage Temperature: -40~+100°C

Grouping parameters:

Forward voltage

Luminous intensity

Dominant wavelength

Soldering methods: Reflow

Preconditioning: acc. to JEDEC Level 3

Packing: Bulk in carton

SMD Display Series

APPLICATIONS:

- 7-Segment Display
- **Double Digital Display**
- Information Board
- White Goods Counter

Release Date: 26 November 2019 Version: A1.0



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current *	IF	20	mA
Peak Forward Current Duty 1/10 @1KHz	I _{FP}	100	mA
Reverse Voltage	VR	5	V
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	48	mW
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T_{STG}	-40~+100	°C

^{1.} All parameters are per diode.

Electrical & Optical Characteristics (Ta=25°C)

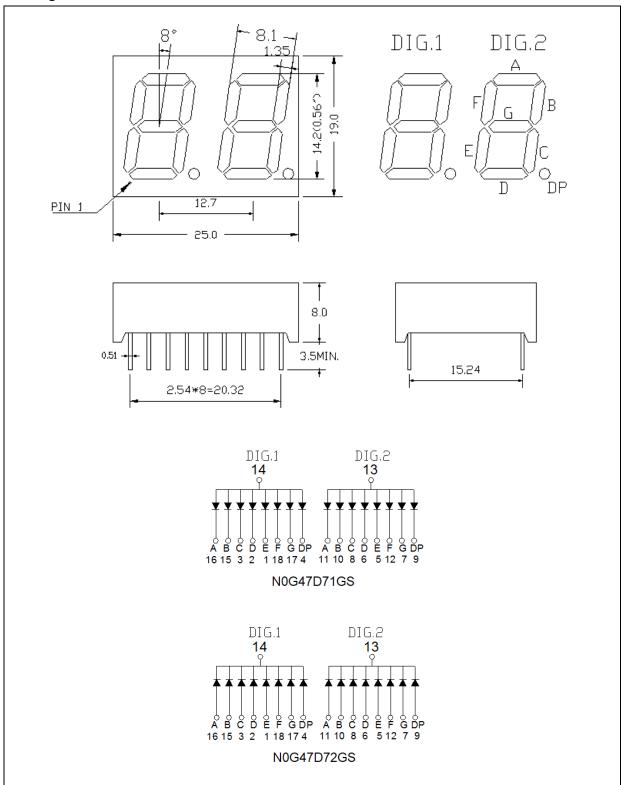
Darameter	Symbol	Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	1.8	2.0	2.4	V	I _F =20mA
Luminous Intensity	lv	9	18		mcd	I _F =20mA
Peak Wavelength	λ_{P}		570		nm	I _F =20mA
Dominant Wavelength	λ_{D}	570	572	574	nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		20		nm	I _F =20mA

^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%



OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
V	1.8	2.4	V

Luminous Intensity Classifications (I_F = 20mA):

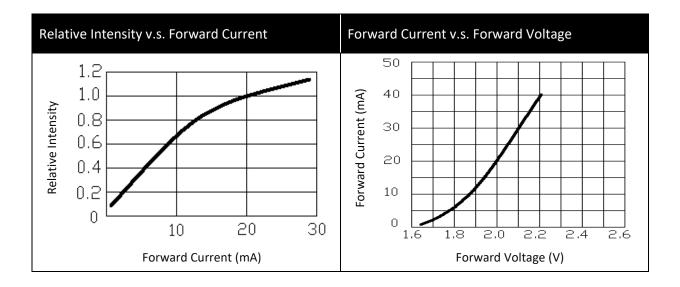
Code	Min.	Max.	Unit
IV	9	32	mcd

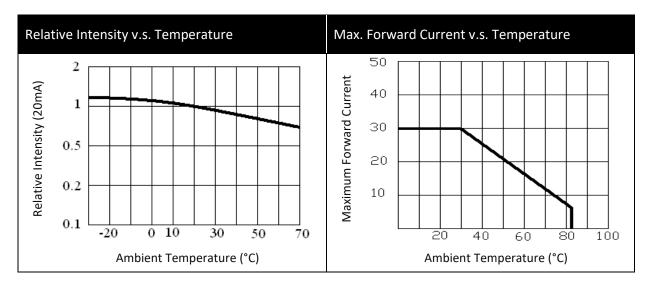
Dominant Wavelength Classifications (I_F = 20mA):

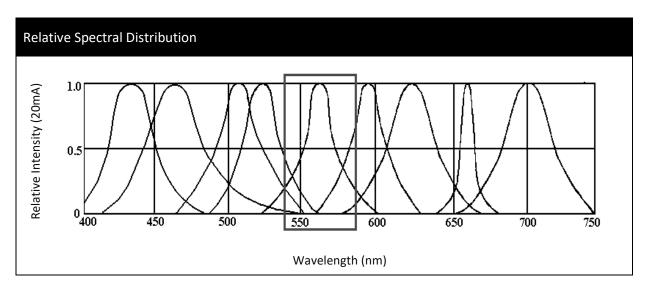
Code	Min.	Max.	Unit
G	570	574	nm



ELECTRO-OPTICAL CHARACTERISTICS:







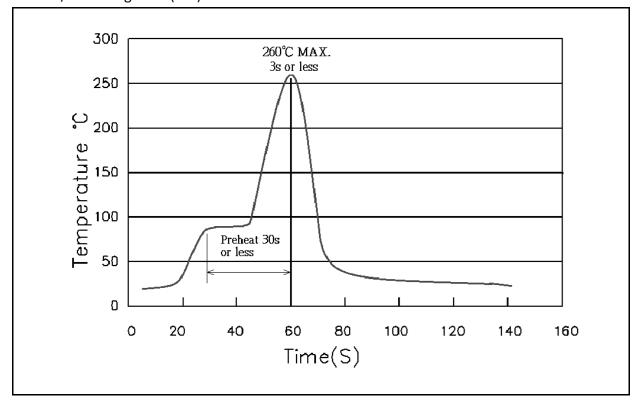


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.
- Maximum reflow soldering: 1 time.

Wave / Soldering Heat (DIP):

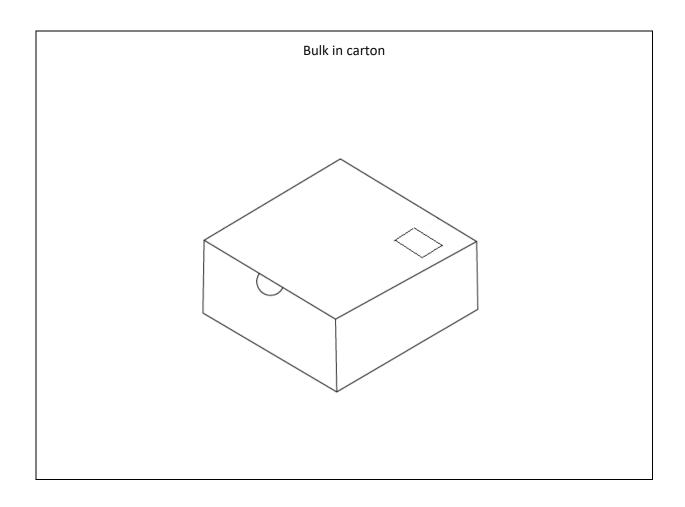


Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking.

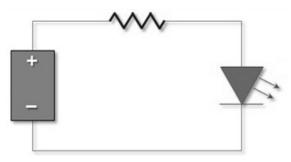
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	26/11/2019	Datasheet set-up.